Stanford

Pingyu Wang

Ph.D. Student in Materials Science and Engineering, admitted Autumn 2017

Publications

PUBLICATIONS

- **A 1024-Channel 268-nW/Pixel 36 x 36 µm²/Channel Data-Compressive Neural Recording IC for High-Bandwidth Brain-Computer Interfaces** *IEEE JOURNAL OF SOLID-STATE CIRCUITS*
  Jang, M., Hays, M., Yu, W., Lee, C., Caragiulo, P., Ramkaj, A. T., Wang, P., Phillips, A. J., Vitale, N., Tandon, P., Yan, P., Mak, P., Chae, et al
  2023

- **A CMOS-based highly scalable flexible neural electrode interface.** *Science advances*
  Zhao, E. T., Hull, J. M., Mintz Hemed, N., Ulu#an, H., Bartram, J., Zhang, A., Wang, P., Pham, A., Ronchi, S., Huguenard, J. R., Hierlemann, A., Melosh, N. A.
  2023; 9 (23): eadf9524

- **Direct-print three-dimensional electrodes for large- scale, high-density, and customizable neural inter- faces.** *bioRxiv : the preprint server for biology*
  Wang, P., Wu, E. G., Ulu#an, H., Phillips, A. J., Rose Hays, M., Kling, A., Zhao, E. T., Madugula, S., Vilkhu, R. S., Vasireddy, P. K., Hier-Lemann, A., Hong, G., Chichilnisky, et al
  2023

- **Automated and Wireless Accelerated Heat Soak Testing System to Assess Hermetic Failure Mechanism of Inductively Powered Implantable Medical Applications** *ADVANCED MATERIALS TECHNOLOGIES*
  Yeon, P., Kim, M., Wang, P., Kim, C., Brand, O., Ghovanloo, M.
  2023

- **A scalable bonding technique for the development of next-generation brain-machine interfaces**
  Wang, P., Goh, T., Hemed, N., Melosh, N., IEEE
  IEEE.2019: 863–66

- **Direct microfabrication of oxide patterns by local electrodeposition of precisely positioned electrolyte: the case of Cu2O** *SCIENTIFIC REPORTS*
  Wang, P., Roberts, R. C., Ngan, A. W.
  2016; 6: 27423